# STMicroelectronics - ST7FLITE35M6TR Datasheet





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#### Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	16MHz
Connectivity	LINbusSCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	15
Program Memory Size	8KB (8K × 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-50
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st7flite35m6tr

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

# **2 PIN DESCRIPTION**

# Figure 2. 20-Pin QFN Package Pinout



(HS) 20mA high sink capability eix associated external interrupt vector

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MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP6 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

**Note:** When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instruc-

Figure 11. Stack Manipulation Example

tions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in Figure 11.

- When an interrupt is received, the SP is decremented and the context is pushed on the stack.
- On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.



Figure 13. Clock Management Block Diagram

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# 7.4 MULTI-OSCILLATOR (MO)

The main clock of the ST7 can be generated by four different source types coming from the multioscillator block (1 to 16MHz or 32kHz):

- an external source
- 5 crystal or ceramic resonator oscillators
- an internal high frequency RC oscillator

Each oscillator is optimized for a given frequency range in terms of consumption and is selectable through the option byte. The associated hardware configurations are shown in Table 5. Refer to the electrical characteristics section for more details.

## **External Clock Source**

In this external clock mode, a clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC1 pin while the OSC2 pin is tied to ground.

**Note:** when the Multi-Oscillator is not used, PB4 is selected by default as external clock.

## **Crystal/Ceramic Oscillators**

This family of oscillators has the advantage of producing a very accurate rate on the main clock of the ST7. The selection within a list of 4 oscillators with different frequency ranges has to be done by option byte in order to reduce consumption (refer to section 15.1 on page 161 for more details on the frequency ranges). In this mode of the multi-oscillator, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. The loading capacitance values must be adjusted according to the selected oscillator.

These oscillators are not stopped during the RESET phase to avoid losing time in the oscillator start-up phase.

## Internal RC Oscillator

In this mode, the tunable 1%RC oscillator is used as main clock source. The two oscillator pins have to be tied to ground. The calibration is done through the RCCR[7:0] and SICSR[6:5] registers.

Table 5. ST7 Clock Sources



# POWER SAVING MODES (Cont'd)

#### 9.4.0.1 Halt Mode Recommendations

- Make sure that an external event is available to wake up the microcontroller from Halt mode.
- When using an external interrupt to wake up the microcontroller, reinitialize the corresponding I/O as "Input Pull-up with Interrupt" or "floating interrupt" before executing the HALT instruction. The main reason for this is that the I/O may be wrongly configured due to external interference or by an unforeseen logical condition.
- For the same reason, reinitialize the level sensitiveness of each external interrupt as a precautionary measure.
- The opcode for the HALT instruction is 0x8E. To avoid an unexpected HALT instruction due to a program counter failure, it is advised to clear all occurrences of the data value 0x8E from memory. For example, avoid defining a constant in program memory with the value 0x8E.
- As the HALT instruction clears the interrupt mask in the CC register to allow interrupts, the user may choose to clear all pending interrupt bits before executing the HALT instruction. This avoids entering other peripheral interrupt routines after executing the external interrupt routine corresponding to the wake-up event (reset or external interrupt).

#### 9.5 ACTIVE-HALT MODE

ACTIVE-HALT mode is the lowest power consumption mode of the MCU with a real time clock (RTC) available. It is entered by executing the 'HALT' instruction. The decision to enter either in ACTIVE-HALT or HALT mode is given by the LTC-SR/ATCSR register status as shown in the following table:.

LTCSR1 TB1IE bit	ATCSR OVFIE1 bit	ATCSR CK1 bit	ATCSR CK0 bit	Meaning
0	х	х	0	ACTIVE-HALT
0	0	х	х	mode disabled
1	х	х	х	ACTIVE-HALT
х	1	0	1	mode enabled

The MCU can exit ACTIVE-HALT mode on reception of a specific interrupt (see Table 6, "Interrupt Mapping," on page 36) or a RESET.

- When exiting ACTIVE-HALT mode by means of a RESET, a 256 CPU cycle delay occurs. After the start up delay, the CPU resumes operation by fetching the reset vector which woke it up (see Figure 27).
- When exiting ACTIVE-HALT mode by means of an interrupt, the CPU immediately resumes operation by servicing the interrupt vector which woke it up (see Figure 27).

When entering ACTIVE-HALT mode, the I bit in the CC register is cleared to enable interrupts. Therefore, if an interrupt is pending, the MCU wakes up immediately (see Note 3).

In ACTIVE-HALT mode, only the main oscillator and the selected timer counter (LT/AT) are running to keep a wake-up time base. All other peripherals are not clocked except those which get their clock supply from another clock generator (such as external or auxiliary oscillator).

**Note:** As soon as ACTIVE-HALT is enabled, executing a HALT instruction while the Watchdog is active does not generate a RESET.

This means that the device cannot spend more than a defined delay in this power saving mode.



# WATCHDOG TIMER (Cont'd)

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
002Eh	WDGCR	WDGA	T6	T5	T4	T3	T2	T1	T0
	Reset Value	0	1	1	1	1	1	1	1

# Table 15. Watchdog Timer Register Map and Reset Values

# DUAL 12-BIT AUTORELOAD TIMER 3 (Cont'd)



## Figure 37. PWM Function

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# SERIAL PERIPHERAL INTERFACE (cont'd)

## 11.4.3.3 Master Mode Operation

In master mode, the serial clock is output on the SCK pin. The clock frequency, polarity and phase are configured by software (refer to the description of the SPICSR register).

**Note:** The idle state of SCK must correspond to the polarity selected in the SPICSR register (by pulling up SCK if CPOL = 1 or pulling down SCK if CPOL = 0).

#### How to operate the SPI in master mode

To operate the SPI in master mode, perform the following steps in order:

- 1. Write to the SPICR register:
  - Select the clock frequency by configuring the SPR[2:0] bits.
  - Select the clock polarity and clock phase by configuring the CPOL and CPHA bits. Figure 52 shows the four possible configurations.
     Note: The slave must have the same CPOL and CPHA settings as the master.
- 2. Write to the SPICSR register:
  - Either set the SSM bit and set the SSI bit or clear the SSM bit and tie the SS pin high for the complete byte transmit sequence.
- 3. Write to the SPICR register:
  - Set the MSTR and SPE bits
    <u>Note</u>: MSTR and SPE bits remain set only if SS is high).

**Important note:** if the SPICSR register is not written first, the SPICR register setting (MSTR bit) may be not taken into account.

The transmit sequence begins when software writes a byte in the SPIDR register.

#### 11.4.3.4 Master Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MOSI pin most significant bit first.

When data transfer is complete:

- The SPIF bit is set by hardware.
- An interrupt request is generated if the SPIE bit is set and the interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

- 1. An access to the SPICSR register while the SPIF bit is set
- 2. A read to the SPIDR register

**Note:** While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

#### 11.4.3.5 Slave Mode Operation

In slave mode, the serial clock is received on the SCK pin from the master device.

To operate the SPI in slave mode:

- 1. Write to the SPICSR register to perform the following actions:
  - Select the clock polarity and clock phase by configuring the CPOL and CPHA bits (see Figure 52).
     Note: The slave must have the same CPOL and CPHA settings as the master.
  - Manage the  $\overline{SS}$  pin as described in Section 11.4.3.2 and Figure 50. If CPHA = 1 SS must be held low continuously. If CPHA = 0  $\overline{SS}$  must be held low during byte transmission and pulled up between each byte to let the slave write in the shift register.
- 2. Write to the SPICR register to clear the MSTR bit and set the SPE bit to enable the SPI I/O functions.

#### 11.4.3.6 Slave Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MISO pin most significant bit first.

The transmit sequence begins when the slave device receives the clock signal and the most significant bit of the data on its MOSI pin.

When data transfer is complete:

- The SPIF bit is set by hardware.
- An interrupt request is generated if SPIE bit is set and interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

- 1. An access to the SPICSR register while the SPIF bit is set
- 2. A write or a read to the SPIDR register

**Notes:** While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

The SPIF bit can be cleared during a second transmission; however, it must be cleared before the second SPIF bit in order to prevent an Overrun condition (see Section 11.4.5.2).

# LINSCI<sup>TM</sup> SERIAL COMMUNICATION INTERFACE (SCI Mode) (cont'd)

f<sub>CPU</sub>

(16\*PR)\*RR

# 11.5.5.4 Conventional Baud Rate Generation

The baud rates for the receiver and transmitter (Rx and Tx) are set independently and calculated as follows:

$$Tx = \frac{f_{CPU}}{(16*PR)*TR} Rx$$

with:

PR = 1, 3, 4 or 13 (see SCP[1:0] bits)

TR = 1, 2, 4, 8, 16, 32, 64,128

(see SCT[2:0] bits)

RR = 1, 2, 4, 8, 16, 32, 64,128

(see SCR[2:0] bits)

All these bits are in the SCIBRR register.

**Example:** If  $f_{CPU}$  is 8 MHz (normal mode) and if PR = 13 and TR = RR = 1, the transmit and receive baud rates are 38400 baud.

**Note:** The baud rate registers MUST NOT be changed while the transmitter or the receiver is enabled.

## 11.5.5.5 Extended Baud Rate Generation

The extended prescaler option gives a very fine tuning on the baud rate, using a 255 value prescaler, whereas the conventional Baud Rate Generator retains industry standard software compatibility.

The extended baud rate generator block diagram is described in Figure 57.

The output clock rate sent to the transmitter or to the receiver will be the output from the 16 divider divided by a factor ranging from 1 to 255 set in the SCIERPR or the SCIETPR register.

**Note:** The extended prescaler is activated by setting the SCIETPR or SCIERPR register to a value other than zero. The baud rates are calculated as follows:

$$Tx = \frac{f_{CPU}}{16 \cdot ETPR^{*}(PR^{*}TR)} Rx = \frac{f_{CPU}}{16 \cdot ERPR^{*}(PR^{*}RR)}$$

with:

ETPR = 1, ..., 255 (see SCIETPR register) ERPR = 1, ..., 255 (see SCIERPR register)



# LINSCI™ SERIAL COMMUNICATION INTERFACE (SCI Mode) (cont'd)

# EXTENDED RECEIVE PRESCALER DIVISION REGISTER (SCIERPR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
ERPR							
7	6	5	4	3	2	1	0

Bits 7:0 = **ERPR[7:0]** 8-bit Extended Receive Prescaler Register

The extended Baud Rate Generator is activated when a value other than 00h is stored in this register. The clock frequency from the 16 divider (see Figure 57) is divided by the binary factor set in the SCIERPR register (in the range 1 to 255).

The extended baud rate generator is not active after a reset.

# EXTENDED TRANSMIT PRESCALER DIVISION REGISTER (SCIETPR)

# Read/Write

Reset Value:0000 0000 (00h)

7							0
ETPR							
7	6	5	4	3	2	1	0

Bits 7:0 = **ETPR[7:0]** 8-bit Extended Transmit Prescaler Register

The extended Baud Rate Generator is activated when a value other than 00h is stored in this register. The clock frequency from the 16 divider (see Figure 57) is divided by the binary factor set in the SCIETPR register (in the range 1 to 255).

The extended baud rate generator is not active after a reset.

**Note:** In LIN slave mode, the Conventional and Extended Baud Rate Generators are disabled.



# LINSCI<sup>TM</sup> SERIAL COMMUNICATION INTERFACE (LIN Mode) (cont'd)









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# LINSCI<sup>TM</sup> SERIAL COMMUNICATION INTERFACE (LIN Mode) (cont'd)

# CONTROL REGISTER 2 (SCICR2)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK

Bits 7:2 Same function as in SCI mode; please refer to Section 11.5.8 SCI Mode Register Description.

## Bit 1 = **RWU** Receiver wake-up.

This bit determines if the SCI is in mute mode or not. It is set and cleared by software and can be cleared by hardware when a wake-up sequence is recognized.

0: Receiver in active mode

1: Receiver in mute mode

## Notes:

- Mute mode is recommended for detecting only the Header and avoiding the reception of any other characters. For more details, please refer to Section 11.5.9.3 LIN Reception.
- In LIN slave mode, when RDRF is set, the software can not set or clear the RWU bit.

## Bit 0 = **SBK** Send break.

This bit set is used to send break characters. It is set and cleared by software.

0: No break character is transmitted

1: Break characters are transmitted

**Note:** If the SBK bit is set to "1" and then to "0", the transmitter will send a BREAK word at the end of the current word.

# **CONTROL REGISTER 3 (SCICR3)**

#### Read/Write

Reset Value: 0000 0000 (00h)

7							0
LDUM	LINE	LSLV	LASE	LHDM	LHIE	LHDF	LSF

Bit 7 = LDUM LIN Divider Update Method.

This bit is set and cleared by software and is also cleared by hardware (when RDRF = 1). It is only used in LIN Slave mode. It determines how the LIN Divider can be updated by software.

0: LDIV is updated as soon as LPR is written (if no Auto Synchronization update occurs at the same time).

1: LDIV is updated at the next received character (when RDRF = 1) after a write to the LPR register

#### Notes:

- If no write to LPR is performed between the setting of LDUM bit and the reception of the next character, LDIV will be updated with the old value.

- After LDUM has been set, it is possible to reset the LDUM bit by software. In this case, LDIV can be modified by writing into LPR / LPFR registers.

Bits 6:5 = **LINE**, **LSLV** *LIN Mode Enable Bits*. These bits configure the LIN mode:

LINE	LSLV	Meaning
0	х	LIN mode disabled
4	0	LIN Master Mode
I	1	LIN Slave Mode

The LIN Master configuration enables:

The capability to send LIN Synch Breaks (13 low bits) using the SBK bit in the SCICR2 register.

- The LIN Slave configuration enables:
  - The LIN Slave Baud Rate generator. The LIN Divider (LDIV) is then represented by the LPR and LPFR registers. The LPR and LPFR registers are read/write accessible at the address of the SCIBRR register and the address of the SCIETPR register
  - Management of LIN Headers.
  - LIN Synch Break detection (11-bit dominant).
  - LIN Wake-Up method (see LHDM bit) instead of the normal SCI Wake-Up method.
  - Inhibition of Break transmission capability (SBK has no effect)
  - LIN Parity Checking (in conjunction with the PCE bit)

## Bit 4 = **LASE** *LIN Auto Synch Enable*.

This bit enables the Auto Synch Unit (ASU). It is set and cleared by software. It is only usable in LIN Slave mode.

0: Auto Synch Unit disabled

1: Auto Synch Unit enabled.

Bit 3 =LHDM *LIN Header Detection Method* This bit is set and cleared by software. It is only usable in LIN Slave mode. It enables the Header Detection Method. In addition if the RWU bit in the



# LINSCI<sup>TM</sup> SERIAL COMMUNICATION INTERFACE (LIN Mode) (cont'd)

SCICR2 register is set, the LHDM bit selects the Wake-Up method (replacing the WAKE bit). 0: LIN Synch Break Detection Method 1: LIN Identifier Field Detection Method

#### Bit 2 = LHIE LIN Header Interrupt Enable

This bit is set and cleared by software. It is only usable in LIN Slave mode.

0: LIN Header Interrupt is inhibited.

1: An SCI interrupt is generated whenever LHDF = 1.

#### Bit 1 = LHDF LIN Header Detection Flag

This bit is set by hardware when a LIN Header is detected and cleared by a software sequence (an access to the SCISR register followed by a read of the SCICR3 register). It is only usable in LIN Slave mode.

0: No LIN Header detected.

1: LIN Header detected.

**Notes:** The header detection method depends on the LHDM bit:

- If LHDM = 0, a header is detected as a LIN Synch Break.
- If LHDM = 1, a header is detected as a LIN Identifier, meaning that a LIN Synch Break Field + a LIN Synch Field + a LIN Identifier Field have been consecutively received.

#### Bit 0 = LSF LIN Synch Field State

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This bit indicates that the LIN Synch Field is being analyzed. It is only used in LIN Slave mode. In Auto Synchronization Mode (LASE bit = 1), when the SCI is in the LIN Synch Field State it waits or counts the falling edges on the RDI line.

It is set by hardware as soon as a LIN Synch Break is detected and cleared by hardware when the LIN Synch Field analysis is finished (see Figure 65). This bit can also be cleared by software to exit LIN Synch State and return to idle mode.

0: The current character is not the LIN Synch Field

1: LIN Synch Field State (LIN Synch Field undergoing analysis)

## Figure 65. LSF Bit Set and Clear



## LIN DIVIDER REGISTERS

LDIV is coded using the two registers LPR and LP-FR. In LIN Slave mode, the LPR register is accessible at the address of the SCIBRR register and the LPFR register is accessible at the address of the SCIETPR register.

## LIN PRESCALER REGISTER (LPR)

#### **Read/Write**

Reset Value: 0000 0000 (00h)

7							0
LPR7	LPR6	LPR5	LPR4	LPR3	LPR2	LPR1	LPR0

#### **LPR[7:0]** *LIN Prescaler (mantissa of LDIV)*

These 8 bits define the value of the mantissa of the LIN Divider (LDIV):

LPR[7:0]	Rounded Mantissa (LDIV)
00h	SCI clock disabled
01h	1
FEh	254
FFh	255

**Caution:** LPR and LPFR registers have different meanings when reading or writing to them. Consequently bit manipulation instructions (BRES or BSET) should never be used to modify the LPR[7:0] bits, or the LPFR[3:0] bits.

Table 22. ADC Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0034h	ADCCSR	EOC	SPEED	ADON	0	0	CH2	CH1	CH0
	Reset Value	0	0	0	0	0	0	0	0
0035h	ADCDRH	D9	D8	D7	D6	D5	D4	D3	D2
	Reset Value	0	0	0	0	0	0	0	0
0036h	ADCDRL	0	0	0	0	SLOW	0	D1	D0
	Reset Value	0	0	0	0	0	0	0	0



# INSTRUCTION GROUPS (cont'd)

Mnemo	Description	Function/Example	Dst	Src	н	I	Ν	Ζ	С
JRULE	Jump if $(C + Z = 1)$	Unsigned <=							
LD	Load	dst <= src	reg, M	M, reg			Ν	Z	
MUL	Multiply	X,A = X * A	A, X, Y	X, Y, A	0				0
NEG	Negate (2's compl)	neg \$10	reg, M				Ν	Z	С
NOP	No Operation								
OR	OR operation	A = A + M	А	М			Ν	Z	
POP	Pop from the Stack	pop reg	reg	М					
		pop CC	СС	М	Н	Ι	Ν	Z	С
PUSH	Push onto the Stack	push Y	М	reg, CC					
RCF	Reset carry flag	C = 0							0
RET	Subroutine Return								
RIM	Enable Interrupts	l = 0				0			
RLC	Rotate left true C	C <= Dst <= C	reg, M				Ν	Z	С
RRC	Rotate right true C	C => Dst => C	reg, M				Ν	Z	С
RSP	Reset Stack Pointer	S = Max allowed							
SBC	Subtract with Carry	A = A - M - C	А	М			Ν	Z	С
SCF	Set carry flag	C = 1							1
SIM	Disable Interrupts	l = 1				1			
SLA	Shift left Arithmetic	C <= Dst <= 0	reg, M				Ν	Z	С
SLL	Shift left Logic	C <= Dst <= 0	reg, M				Ν	Z	С
SRL	Shift right Logic	0 => Dst => C	reg, M				0	Z	С
SRA	Shift right Arithmetic	Dst7 => Dst => C	reg, M				Ν	Z	С
SUB	Subtraction	A = A - M	А	М			Ν	Z	С
SWAP	SWAP nibbles	Dst[74] <=> Dst[30]	reg, M				Ν	Z	
TNZ	Test for Neg & Zero	tnz lbl1					Ν	Z	
TRAP	S/W trap	S/W interrupt				1			
WFI	Wait for Interrupt					0			
XOR	Exclusive OR	A = A XOR M	А	М			Ν	Z	

## **13.2 ABSOLUTE MAXIMUM RATINGS**

Stresses above those listed as "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these condi-

#### 13.2.1 Voltage Characteristics

tions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Symbol	Ratings	Maximum value	Unit
V <sub>DD</sub> - V <sub>SS</sub>	Supply voltage	7.0	V
V <sub>IN</sub>	Input voltage on any pin <sup>1) &amp; 2)</sup>	$V_{\rm SS}\mbox{-}0.3$ to $V_{\rm DD}\mbox{+}0.3$	v
V <sub>ESD(HBM)</sub>	Electrostatic discharge voltage (Human Body Model)	see section 13.7.3 on pa	age 147

#### **13.2.2 Current Characteristics**

Symbol	Ratings	Maximum value	Unit
I <sub>VDD</sub>	Total current into $V_{DD}$ power lines (source) <sup>3)</sup>	75	
I <sub>VSS</sub>	Total current out of $V_{SS}$ ground lines (sink) <sup>3)</sup>	150	
	Output current sunk by any standard I/O and control pin	20	
I <sub>IO</sub>	Output current sunk by any high sink I/O pin	40	
	Output current source by any I/Os and control pin	-25	m 4
	Injected current on RESET pin	±5	
I <sub>INJ(PIN)</sub> <sup>2) &amp; 4)</sup>	Injected current on OSC1 and OSC2 pins	±5	
	Injected current on PB0 and PB1 pins 5)	+5	
	Injected current on any other pin 5)	±5	
$\Sigma I_{\rm INJ(PIN)}^{(2)}$	Total injected current (sum of all I/O and control pins) 5)	±20	

#### 13.2.3 Characteristics

Symbol	Ratings	Value	Unit			
T <sub>STG</sub>	Storage temperature range	-65 to +150 °C				
TJ	Maximum junction temperature (see section 14.2 on page	je 160)				

#### Notes:

**1.** Directly connecting the RESET and I/O pins to  $V_{DD}$  or  $V_{SS}$  could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical:  $4.7k\Omega$  for RESET,  $10k\Omega$  for I/Os). Unused I/O pins must be tied in the same way to  $V_{DD}$  or  $V_{SS}$  according to their reset configuration. **2.**  $I_{INJ(PIN)}$  must never be exceeded. This is implicitly insured if  $V_{IN}$  maximum is respected. If  $V_{IN}$  maximum cannot be respected, the injection current must be limited externally to the  $I_{INJ(PIN)}$  value. A positive injection is induced by  $V_{IN}$ - $V_{DD}$  while a negative injection is induced by  $V_{IN}$ - $V_{SS}$ . For true open-drain pads, there is no positive injection current, and the corresponding  $V_{IN}$  maximum must always be respected.

3. All power ( $V_{DD}$ ) and ground ( $V_{SS}$ ) lines must always be connected to the external supply.

4. Negative injection disturbs the analog performance of the device. In particular, it induces leakage currents throughout the device including the analog inputs. To avoid undesirable effects on the analog functions, care must be taken:

- Analog input pins must have a negative injection less than 0.8 mA (assuming that the impedance of the analog voltage is lower than the specified limits)

- Pure digital pins must have a negative injection less than 1.6mA. In addition, it is recommended to inject the current as far as possible from the analog input pins.

5. When several inputs are submitted to a current injection, the maximum  $\Sigma I_{INJ(PIN)}$  is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterisation with  $\Sigma I_{INJ(PIN)}$  maximum current injection on four I/O port pins of the device.



# **OPERATING CONDITIONS** (Cont'd)

# 13.3.1.2 Devices with tested for $T_A$ = -40 to +125°C @ $V_{DD}$ = 3.0 to 3.6V

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
£ 1)	Internal RC oscillator fre-	RCCR = FF (reset value), T <sub>A</sub> =25°C, V <sub>DD</sub> = 3.3V		630		kU-
IRC /	quency	RCCR=RCCR1 <sup>2)</sup> ,T <sub>A</sub> =25°C,V <sub>DD</sub> = 3.3V	995	1000	1005	КПZ
	Accuracy of Internal RC	T <sub>A</sub> =25°C, V <sub>DD</sub> =3.0 to 3.6V	-1		+1	
ACC <sub>RC</sub>	oscillator when calibrated	$T_A$ =-40 to +85°C, $V_{DD}$ =3.0 to 3.6V	-3		+3	%
	with RCCR=RCCR1 <sup>2)3)</sup>	T <sub>A</sub> =-40 to +125°C, V <sub>DD</sub> =3.0 to 3.6V	-3		+3	
I <sub>DD(RC)</sub>	RC oscillator current con- sumption	T <sub>A</sub> =25°C,V <sub>DD</sub> =3.3V		500 <sup>3)4)</sup>		μA
t <sub>su(RC)</sub>	RC oscillator setup time	T <sub>A</sub> =25°C,V <sub>DD</sub> =3.3V			10 <sup>2)</sup>	μs
f <sub>PLL</sub>	x4 PLL input clock			1		MHz
t <sub>LOCK</sub>	PLL Lock time <sup>7)</sup>			2		ms
t <sub>STAB</sub>	PLL Stabilization time <sup>7)</sup>			4		ms
100	v4 PLL Acoursov	$f_{RC} = 1MHz@T_A=25°C, V_{DD}=2.7 \text{ to } 3.3V$		0.1 <sup>6)</sup>		%
ACCPLL	X4 FLL Accuracy	$f_{RC} = 1MHz@T_A = -40 \text{ to } +125^{\circ}C, V_{DD} = 3.3V$		0.1 <sup>6)</sup>		%
t <sub>w(JIT)</sub>	PLL jitter period	f <sub>RC</sub> = 1MHz		8 <sup>5)</sup>		kHz
JIT <sub>PLL</sub>	PLL jitter (∆f <sub>CPU</sub> /f <sub>CPU</sub> )			1 <sup>5)</sup>		%
I <sub>DD(PLL)</sub>	PLL current consumption	T <sub>A</sub> =25°C		450 <sup>3)</sup>		μA

#### Notes:

1. If the RC oscillator clock is selected, to improve clock stability and frequency accuracy, it is recommended to place a decoupling capacitor, typically 100nF, between the  $V_{DD}$  and  $V_{SS}$  pins as close as possible to the ST7 device.

- 2. See "INTERNAL RC OSCILLATOR ADJUSTMENT" on page 23.
- $\ensuremath{\textbf{3.}}$  Data based on characterization results, not tested in production
- 4. Measurement made with RC calibrated at 1MHz.

5. Guaranteed by design.

6. Averaged over a 4ms period. After the LOCKED bit is s et, a period of t<sub>STAB</sub> is required to reach ACC<sub>PLL</sub> accuracy

7. After the LOCKED bit is set ACC<sub>PLL</sub> is max. 10% until t<sub>STAB</sub> has elapsed. See Figure 12 on page 24.



# **13.9 CONTROL PIN CHARACTERISTICS**

## 13.9.1 Asynchronous RESET Pin

 $T_A = -40^{\circ}C$  to 125°C, unless otherwise specified

Symbol	Parameter		Conditions	Min	Тур	Max	Unit
V <sub>IL</sub>	Input low level voltage			V <sub>SS</sub> - 0.3		$0.3 \mathrm{xV}_\mathrm{DD}$	V
V <sub>IH</sub>	Input high level voltage			$0.7 \mathrm{xV}_{\mathrm{DD}}$		V <sub>DD</sub> + 0.3	v
V <sub>hys</sub>	Schmitt trigger voltage hysteresis 1)				1		V
Va	Output low lovel voltage 2)	V <b>5</b> V	I <sub>IO</sub> =+5mA T <sub>A</sub> ≤125°C T <sub>A</sub> ≥125°C		0.5 -	1.0 1.2	V
VOL	Output low level voltage	V <sub>DD</sub> =5V	I <sub>IO</sub> =+2mA T <sub>A</sub> ≤125°C T <sub>A</sub> ≥125°C		0.45 -	0.7 0.9	v
Bau	Pull-up equivalent resistor $^{3)}$ <sup>1)</sup>	V <sub>DD</sub> =5V	T <sub>A</sub> ≤125°C	10	46	70	kΩ
ON	i ul-up equivalent resistor a a	V <sub>DD</sub> =3V			91		kΩ
t <sub>w(RSTL)out</sub>	Generated reset pulse duration	Internal reset sources			30		μS
t <sub>h(RSTL)in</sub>	External reset pulse hold time 4)			20			μS
t <sub>g(RSTL)in</sub>	Filtered glitch duration				200		ns

#### Notes:

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1. Data based on characterization results, not tested in production.

2. The I<sub>IO</sub> current sunk must always respect the absolute maximum rating specified in section 13.2.2 on page 132 and the sum of I<sub>IO</sub> (I/O ports and control pins) must not exceed I<sub>VSS</sub>.

3. The  $R_{ON}$  pull-up equivalent resistor is based on a resistive transistor. Specified for voltages on  $\overline{\text{RESET}}$  pin between  $V_{\text{ILmax}}$  and  $V_{\text{DD}}$ 

**4.** To guarantee the reset of the device, a minimum pulse has to be applied to the  $\overrightarrow{\text{RESET}}$  pin. All short pulses applied on RESET pin with a duration below  $t_{h(\text{RSTL})in}$  can be ignored.

# **15 DEVICE CONFIGURATION**

Each device is available for production in user programmable versions (FLASH) as well as in factory coded versions (ROM/FASTROM).

ST7PLITE3 devices are Factory Advanced Service Technique ROM (FASTROM) versions: they are factory programmed FLASH devices.

# **15.1 FLASH OPTION BYTES**

The two option bytes allow the hardware configuration of the microcontroller to be selected.

# **OPTION BYTE 0**

## OPT7 = AWUCK Auto Wake Up Clock Selection

0: 32-KHz Oscillator (VLP) selected as AWU clock

1: AWU RC Oscillator selected as AWU clock.

**Note:** If this bit is reset, internal RC oscillator must be selected (Option OSC=0).

## OPT6:4 = OSCRANGE[2:0] Oscillator Range

When the internal RC oscillator is not selected (Option OSC=1), these option bits select the range of the resonator oscillator current source or the external clock source.

		os	CRAN	GE	
			2	1	0
	LP	1~2MHz	0	0	0
Тур.	MP	2~4MHz	0	0	1
frequency range with Resonator	MS	4~8MHz	0	1	0
	HS	8~16MHz	0	1	1
	VLP	32.768kHz	1	0	0
External (	1	0	1		
Re	1	1	0		
External	External Clock on PB4				1

#### Notes:

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1. OSCRANGE[2:0] has no effect when AWUCK option is set to 0. In this case, the VLP oscillator range is automatically selected as AWU clock.

2. When the internal RC oscillator is selected, the OSCRANGE option bits must be kept at their default value to select the 256 clock cycle delay (see section 7.5 on page 27)

ST7FLITE3 devices are shipped to customers with a default program memory content (FFh), while FASTROM factory coded parts contain the code supplied by the customer. This implies that FLASH devices have to be configured by the customer using the Option Bytes.

OPT 3:2 = <b>SEC[1:0]</b> Sector 0 size definition
These option bits indicate the size of sector 0 ac-
cording to the following table.

Sector 0 Size	SEC1	SEC0
0.5k	0	0
1k	0	1
2	1	0
4k	1	1

#### OPT1 = FMP\_R Read-out protection

Readout protection, when selected provides a protection against program memory content extraction and against write access to Flash memory. Erasing the option bytes when the FMP\_R option is selected will cause the whole memory to be erased first and the device can be reprogrammed. Refer to the ST7 Flash Programming Reference Manual and section 4.5 on page 14 for more details

0: Read-out protection off

1: Read-out protection on

#### OPT 0 = **FMP\_W** FLASH write protection

This option indicates if the FLASH program memory is write protected.

**Warning:** When this option is selected, the program memory (and the option bit itself) can never be erased or programmed again.

0: Write protection off

1: Write protection on

The option bytes have no address in the memory map and can be accessed only in programming mode (for example using a standard ST7 programming tool). The default content of the FLASH is fixed to FFh.

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# **OPTION BYTES** (Cont'd)

	OPTION BYTE 0									0	PTION	BYTE	1			
	7							0	7							0
	AWU CK	OS	CRAN 2:0	GE	SEC1	SEC0	FMPR	FMPW	PLL x4x8	PLL OFF	Res.	OSC	L\ 1	/D :0	WDG SW	WDG HALT
Default Value	1	1	1	1	1	1	0	0	1	1	1	0	1	1	1	1

## **OPTION BYTE 1**

OPT 7 = **PLLx4x8** *PLL Factor Selection.* 0: PLLx4 1: PLLx8

OPT 6 = **PLLOFF** *PLL Disable* This option bit enables or disables the PLL.

0: PLL enabled

1: PLL disabled (bypassed)

OPT 5 = Reserved. Must always be set to 1.

OPT 4 = **OSC** RC Oscillator Selection

This option bit enables to select the internal RC Oscillator.

0: RC Oscillator on

1: RC Oscillator off

#### Notes:

- RC oscillator available on ST7LITE35 and ST7LITE39 devices only
- If the RC oscillator is selected, then to improve clock stability and frequency accuracy, it is recommended to place a decoupling capacitor, typically 100nF, between the V<sub>DD</sub> and V<sub>SS</sub> pins as close as possible to the ST7 device.

OPT 3:2 = **LVD[1:0]** Low Voltage Selection These option bits enable the voltage detection block (LVD and AVD) with a selected threshold to the LVD and AVD.

Configuration	VD1	VD0
LVD Off	1	1
Highest Voltage Threshold	1	0
Medium Voltage Threshold	0	1
Lowest Voltage Threshold	0	0

OPT 1 = **WDGSW** Hardware or Software Watchdog

0: Hardware (watchdog always enabled)

1: Software (watchdog to be enabled by software)

OPT 0 = WDG HALT Watchdog Reset on Halt

0: No reset generation when entering HALT mode

1: Reset generation when entering HALT mode

